



Material Content Data Sheet



Sales Product Name				IPD90N06S4-07		Issued		20. July 2018	
MA#				MA001036678					
Package				PG-TO252-3-11		Weight*		374.83 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.466	0.66	0.66	6579	6579	
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		574		
	inorganic material	phosphorus	7723-14-0	0.065	0.02		172		
	non noble metal	copper	7440-50-8	215.017	57.36	57.44	573640	574386	
wire	non noble metal	aluminium	7429-90-5	39.882	10.64	10.64	106401	106401	
encapsulation	organic material	carbon black	1333-86-4	0.917	0.24		2448		
	plastics	epoxy resin	-	16.056	4.28		42834		
	inorganic material	silicondioxide	60676-86-0	74.773	19.95	24.47	199485	244767	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	9978	9978	
plating	non noble metal	nickel	7440-02-0	0.091	0.02		242		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	243	
solder	noble metal	silver	7440-22-4	0.060	0.02		160		
	non noble metal	tin	7440-31-5	0.048	0.01		128		
	non noble metal	lead	7439-92-1	2.297	0.61	0.64	6129	6417	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		51		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		15		
	non noble metal	copper	7440-50-8	19.177	5.12	5.13	51163	51229	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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